

Amendments to the Claims:

This listing of claims will replace all prior versions, and listings, of claims in the application.

Listing of Claims:

Claims 1-12 (canceled)

Claim 13 (amended): ~~An interconnect assembly as in claim 2~~ An interconnect assembly comprising:

a substrate;

a resilient contact element having at least a portion thereof which is capable of moving to a first position in which said resilient contact element is in mechanical and electrical contact with another contact element, said resilient contact element being disposed on said substrate;

a stop structure disposed on said substrate, said stop structure defining said first position, wherein said another contact element is disposed on another substrate, and wherein said stop structure defines a separation between said substrate and said another substrate when said resilient contact element is in mechanical and electrical contact with said another contact element, and

wherein said stop structure is formed from a sheet material in which an opening exists and said resilient contact element is disposed in said opening.

Claim 14 (original): An interconnect assembly as in claim 13 wherein a plurality of resilient contact elements are disposed on said substrate in corresponding openings in said sheet material which is disposed on said substrate.

Claim 15 (original): An interconnect assembly as in claim 14 wherein said sheet material comprises an adhesive layer.

Claims 16-19 (canceled)

Claim 20 (amended): ~~An interconnect assembly as in claim 17~~ An interconnect assembly comprising:

a first substrate;

a first contact element disposed on said first substrate;

a stop structure disposed on said first substrate, said stop structure defining a first position of a resilient contact element in which said resilient contact element is in mechanical and electrical contact with said first contact element,

wherein said resilient contact element is disposed on a second substrate and wherein said resilient contact element has at least a portion thereof which is capable of moving to said first position when said resilient contact element is compressed, and

wherein said stop structure comprises an adhesive layer.

Claim 21 (original): An interconnect assembly as in claim 20 wherein said adhesive layer is for bonding to said another substrate.

Claims 22-27 (canceled)

Claim 28 (amended): ~~An interconnect assembly as in claim 17~~ An interconnect assembly comprising:

a first substrate;

a first contact element disposed on said first substrate;

a stop structure disposed on said first substrate, said stop structure defining a first position of a resilient contact element in which said resilient contact element is in mechanical and electrical contact with said first contact element,

wherein said resilient contact element is disposed on a second substrate and wherein said resilient contact element has at least a portion thereof which is capable of moving to said first position when said resilient contact element is compressed, and

wherein said stop structure is formed from a sheet material in which an opening exists and said first contact element is disposed in said opening.

Claim 29 (original): An interconnect assembly as in claim 28 wherein a plurality of first contact elements are disposed on said first substrate in corresponding openings in said sheet material which is disposed on said substrate.

Claim 30 (original): An interconnect assembly as in claim 29 wherein said sheet material comprises an adhesive layer.

Claim 33 (original): A method for forming a stop structure on a substrate, said method comprising:

forming a plurality of openings in a sheet;

applying said sheet to a substrate;

forming a plurality of contact elements on said substrate in locations corresponding to said plurality of openings, wherein said sheet comprises at least one region disposed around at least one of said openings which is said stop structure.

Claim 34 (original): A method as in claim 33 wherein said stop structure defines a first position of a resilient contact member on another substrate in which said resilient contact member is in mechanical and electrical contact with one of said contact elements in said at least one of said openings.

Claim 35 (original): A method as in claim 33 wherein each of said contact elements comprises a resilient contact element disposed on said substrate and which is capable of moving to a first position and wherein said stop structure defines said first position in which said resilient contact element is in mechanical and electrical contact with another contact element on another substrate.

Claim 36 (original): A method as in claim 33 wherein said substrate is a wafer of semiconductor integrated circuits and said sheet fits on said wafer.

Claim 37 (original): A method as in claim 33 wherein said sheet comprises a polyimide material.

Claim 38 (original): A method as in claim 33 further comprising applying an adhesive layer to said sheet.

Claim 39 (original): A method as in claim 33 wherein said plurality of openings is formed before applying said sheet to said substrate and wherein said plurality of contacts are formed before said sheet is applied to said substrate.

Claim 40 (original): A method as in claim 33 wherein said plurality of openings is formed after applying said sheet to said substrate.

Claims 41-50 (canceled)

Claim 51 (original): A method for forming a stop structure on a substrate, said method comprising:

applying a sheet to said substrate;
forming at least one first contact element on said substrate, said first contact element having a first height relative to said substrate and said sheet having a second height relative to said substrate, said sheet defining a minimum separation which is capable of existing between said substrate and another substrate having a second contact element which is in mechanical and electrical contact with said first contact element when said minimum separation exists.

Claim 52 (original): A method as in claim 51 wherein said sheet is a perimeter stop structure.

Claim 53 (original): A method as in claim 51 wherein said first contact element is a resilient contact element and said first height is greater than said second height.

Claim 54 (original): A method as in claim 51 wherein said second contact element is a resilient contact element and said first height is less than said second height.

Claim 55 (original): A method as in claim 51 wherein said sheet comprises an adhesive material which secures said sheet to said substrate.

Claim 56 (original): A method as in claim 51 wherein said sheet covers only a portion of said substrate.

Claim 57 (original): A method as in claim 51 further comprising:

forcing together said substrate and said another substrate such that they are separated by said minimum separation.